

Università degli Studi di Padova Dipartimento di Ingegneria Industriale



### **Energy and Buildings**

### Calculation of a thermal bridge using FEMM 4.2

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# Thermal bridge

### Definition (ISO 10211)

Part of the building envelope where the otherwise uniform thermal resistance is significantly <u>changed</u>

- by full or partial penetration of the building envelope by materials with a different thermal conductivity;
- by change in thickness of the fabric or difference between internal and external areas such as occur at wall/floor/ceiling junctions.





# Thermal bridge

Change of thermal transmittance due to a discontinuity in the **materials** or **geometry** of the building envelope



- Additional heat flow has an impact on energy needs
- Local decrease of internal surface temperature may cause
  **condensation** problems in the heating season





# Objectives

Use a software for the calculation of thermal bridges in building constructions:

- Calculate additional heat flow in thermal bridges (according to ISO 10211)
- 2. Assess the risk of surface condensation (according to ISO 13788)

FEMM 4.2 http://www.femm.info/wiki/Download





## Heat conduction in solids

Analytical solution for 1D steady-state problem on a composite wall



Equivalent thermal circuit for a composite wall (Incropera & DeWitt, 1981)

$$\frac{\partial}{\partial x} \left( k_x \frac{\partial T}{\partial x} \right) = 0$$

#### **ELECTRICAL ANALOGY (1)** Fix temperature difference $(T_1 - T_2) \rightarrow$

q

find heat flow  $q_x$ 

$$x = \frac{(T_1 - T_2)}{\sum_i R_i}$$

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### Heat loss coefficient







### **Transmission heat transfer coefficient**

$$q_{T} = H_{T} (\theta_{i} - \theta_{e}) \begin{cases} H_{T} = \sum_{i} U_{i} A_{i} \\ H_{T} = \sum_{i} U_{i} A_{i} + \sum_{j} \Psi_{j} l_{j} + \sum_{k} \chi_{k} \end{cases}$$





## Calculation method of ISO 10211

Geometrical model	Example	Method
2D	F2 F2 F4	Linear thermal transmittance, $\Psi$ (W/(m K)) Thermal coupling coefficient from 2D calculation, $L_{2D}$ (W/(m K)) $\Psi = L_{2D} - \sum_{j=1}^{N_j} U_j l_j$
3D		Point thermal transmittance, $\chi$ (W/K) Thermal coupling coefficient from 3D calculation, $L_{3D}$ (W/K) $\chi = L_{3D} - \sum_{i=1}^{N_i} U_i A_i - \sum_{j=1}^{N_j} \Psi_j l_j$

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## Calculation method of ISO 10211

### Thermal coupling coefficient

The thermal coupling coefficient  $(L_{2D} \text{ or } L_{3D})$  is heat flow rate per temperature difference between two environments which are thermally connected by the construction under consideration.

$$L_{2D} = \frac{Q_{ie}}{l(T_i - T_e)} \left[\frac{W}{m K}\right]$$





#### Calculation of the linear thermal transmittance



- Evaluate temperature distribution with
  2D heat conduction calculation software
- 2. Integrate temperature difference over normal surface to get the heat flow rate  $q_{ie}$  and to calculate the thermal coupling coefficient  $L_{2D}$
- 3. Calculate the linear thermal transmittance according to Standard

$$\Psi = L_{2D} - (U_x l_x + U_y l_y)$$





### Calculation method of ISO 10211

Types of boundary conditions







### Calculation method of ISO 10211



Calculation of the linear thermal transmittance

Minimum distances of cut-off planes for 2D geometrical models is a function of envelope thickness according to the Standard





## **FEMM 4.2**



The FEMM software is a **finite element** package for solving **2D planar** and axisymmetric magnetic, electrostatic, **steadystate heat conduction**, and current flow **problems**.





# Calculation method of ISO 10211

### **Steps for the calculation of the thermal bridge with FEMM 4.2:**

- 1. Import geometry from a .dxf file
- 2. Set material properties for each building component
- 3. Set boundary conditions
- 4. Create a mesh to discretize the domain
- 5. Run the FEM solver to calculate the temperature distribution
- 6. Integrate temperature difference over normal surface
- 7. Calculate  $L_{2D}$ ,  $\psi$  and minimum surface temperature







#### Intermediate floor junction

Material (eng)	Material (it)	Thermal conductivity k [W/(m K)]	Volumetric heat capacity c [MJ/(m3 K)]
Internal plaster	Intonaco interno (calce e gesso)	0.70	1.26
External plaster	Intonaco esterno (calce e cemento)	1.00	1.51
Reinforced concrete	Cemento armato	2.30	2.02
Screed	Massetto (calcestruzzo alleggerito con argilla espansa)	0.45	0.92
Semi-hollow bricks	Laterizio semipieno	0.70	1.01
Hollow bricks	Tramezza in laterizio	0.36	0.92
Ceramic tiles	Piastrelle di ceramica	1.20	1.68
Polistyrene (EPS)	Polistirene espanso (EPS)	0.04	0.05













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**Boundary condition of the II type** Adiabatic surface (q = 0)

#### Boundary conditions of the III type $h_{si} = 8 \text{ W/(m<sup>2</sup> K)}, T_i = 20^{\circ}\text{C}$

 $h_{se} = 25 \text{ W/(m^2 K)}, T_e = 0^{\circ}\text{C}$